Claims

[c1]

1. A solder paste printing method comprising:

a first process for mounting a mask having apertures corresponding to land portions of a printed circuit board, on said printed circuit board at a predetermined position thereof in a state where it is placed in position; a second process for mounting a solder paste containing therein as a solder material a tin-zinc (Sn-Zn) system solder on said mask and for permitting said solder paste to make rolling from one end of said mask toward the opposite end thereof by means of a squeegee, while maintaining moisture contained in the atmosphere surrounding said solder paste at a value equal to or less than a predetermined value, wherein said squeegeeurges said solder paste to make rolling, to thereby fill said solder paste into said apertures; and a third process for separating said mask away from said printed circuit board.

[c2]

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2. The solder paste printing method according to claim 1, wherein said moisture

is equal to or less than 10 g/m^3 .

[c3]

3. The solder paste printing method according to claim 2, wherein said atmosphere mainly comprises a nitrogen gas (N $_2$).

[c4]

4. A solder paste printing apparatus comprising:

a mask having apertures corresponding to land portions of a printed circuit board;

a squeegee urging a solder paste containing therein as a solder material a tin-zinc (Sn-Zn) system solder and mounted on said mask, which is placed in position at a predetermined position on said printed circuit board to make rolling from one end of said mask toward the opposite end thereof; and a moisture regulating means for maintaining moisture contained in the atmosphere surrounding said solder paste at a value equal to or less than a predetermined value.

[c5]

5. The solder paste printing apparatus according to claim 4, wherein said

moisture is equal to or less than 10 g/m^3 .

[c6]

6. The solder paste printing apparatus according to claim 5, wherein said

[c7]

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